VISHAY®

Material Declaration Sheet

Vishay General Semiconductor - PDD

Date	28-Jul-20

Part / Product Family Details

Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemptions Used
SS3P3L-(H)M3 to SS3P4L-(H)M3 SS3P5L-(H)M3 to SS3P6L-(H)M3 SS5P3-(H)M3 to SS5P4-(H)M3 SS5P5-(H)M3 to SS5P6-(H)M3 SS5P9-(H)M3 to SS5P10-(H)M3 SS8P2L-(H)M3 to SS8P3L-(H)M3 SS8PH9-(H)M3 to SS8PH10-(H)M3 SS10P2CL-(H)M3 to SS10P3CL-(H)M3 SS10P2CL-(H)M3 SS15P3S-M3 SS10P3C-(H)M3 to SS10P4C-(H)M3 SS10P3-(H)M3 to SS10P4-(H)M3 SS10P5-(H)M3 to SS10P6-(H)M3 SS10PH9-(H)M3 to SS10PH10-(H)M3 SS10PH35-(H)M3 to SS10PH45-(H)M3 SS12P2L-(H)M3 to SS12P3L-(H)M3 SS12P4C-(H)M3 SS12P4S-(H)M3 SS6P3C-M3 to SS6P4C-M3 SS8P2CL-M3 to SS8P3CL-M3 SS8P3C-M3 to SS8P4C-M3 SS8P5C-M3 to SS8P6C-M3 SS15P3S-M3	YES WITH EXEMPTION	01-12-2004	0.1	N/A	Yes	China	One

Technical Information: refer to http://www.vishay.com/how/leadfree/#summary

Terminal Plating / Grid Array Material	Terminal Base Alloy	JESD-97 Pb-Free Material Code Marking	J-STD-20D MSL Rating	Reflow Peak Process Body Temperature	Reflow Maximum number of cycles	Reflow Max.Time at Peak Temperature (sec)	Soldering Compatibility (SnPb/Pb-Free)

Material Composition

Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm		
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00508	100.00	1000000	5.08	
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.06015	100.00	1000000	60.15	
Solder 92.5	Other special metals	Lead	7439-92-1	0.00076	92.50	925000	0.76	Exemption No:7(a)
		Tin	7440-31-5	0.00004	5.00	50000	0.04	
		Silver	7440-22-4	0.00002	2.50	25000	0.02	
Encapsulation	Other duromers	Fused Silica	60676-86-0	0.02502	78.00	780000	25.02	
		Solid Epoxy Resin-2	71296-97-4	0.00032	1.00	10000	0.32	
		Solid Epoxy Resin	93705-66-9	0.00192	6.00	60000	1.92	
		Phenol Resin	26834-02-6	0.00192	6.00	60000	1.92	
		Metal Hydroxide	1309-42-8	0.00269	8.40	84000	2.69	
		Carbon Black	1333-86-4	0.00019	0.60	6000	0.19	
Surface finish	Other special metals	Tin	7440-31-5	0.00188	100.00	1000000	1.88	

EU-RoHS Directive-2015/863/EU MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium ,Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP)

This MDS vaild for List of PN's

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.
(ii) Substance weight are derived from MSDS.

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Vishay General Semiconductor - PDD
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